

FEATURES

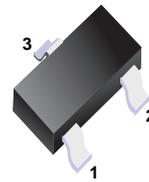
High density cell design for low $R_{DS(ON)}$
Voltage controlled small signal switch
Rugged and reliable
High saturation current capability

APPLICATION

Load Switch for Portable Devices
DC/DC Converter

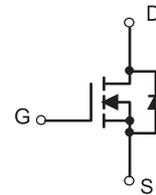
V_{DSS}	60	V
I_D	0.3	A
$R_{DS(ON)}$	0.9	Ω

72K



Simplified outline(SOT-23)

Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Maximum ratings ($T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	0.3	A
Power Dissipation	P_D	0.200	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	625	$^{\circ}\text{C}/\text{W}$
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-50 ~+150	

Electrical Characteristics

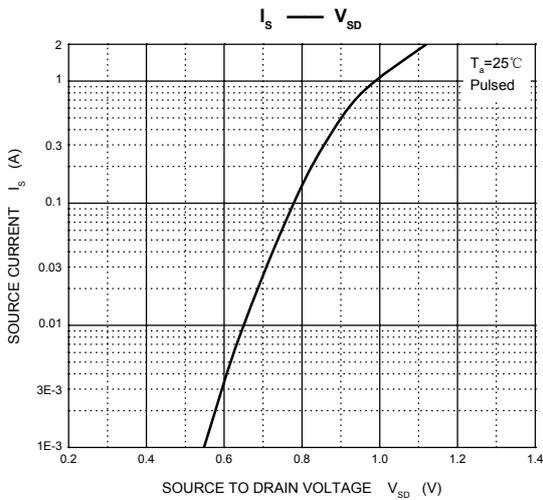
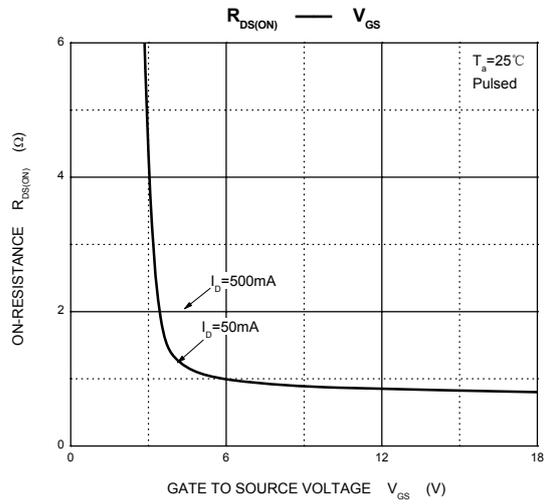
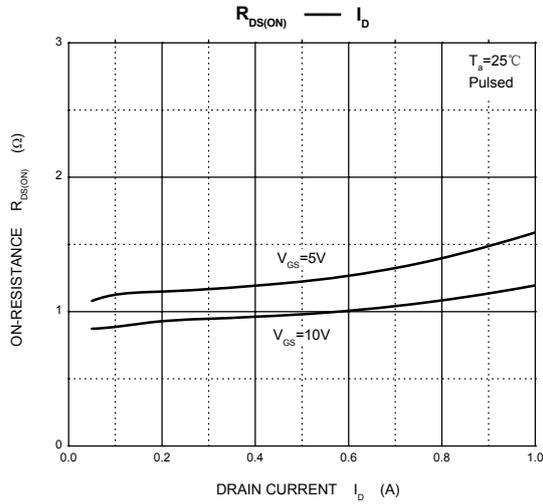
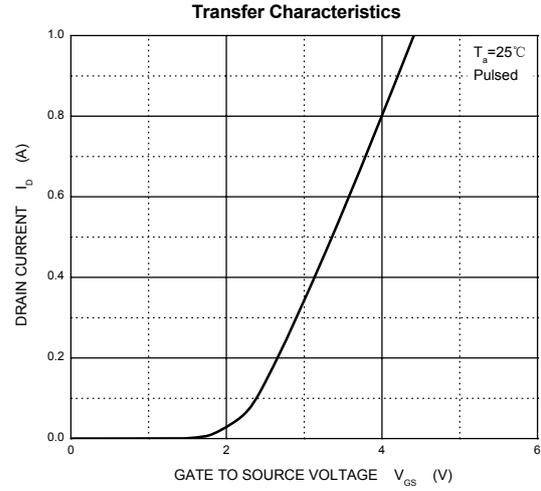
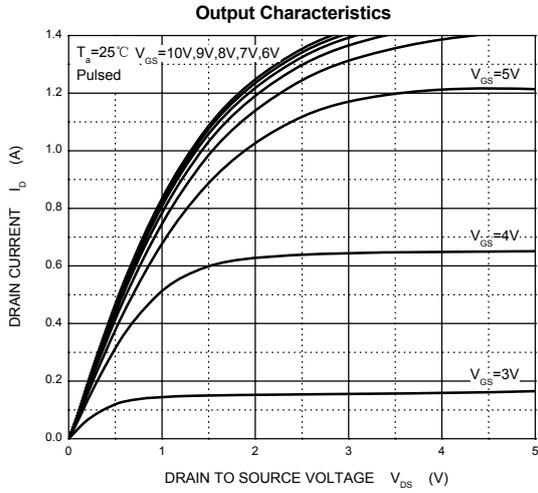
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=250\ \mu\text{A}$	60			V
Gate-Threshold Voltage	$V_{(GS)th}$	$V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$	1	1.6	2.5	V
Gate-body Leakage	I_{GSS}	$V_{DS}=0\text{ V}, V_{GS}=\pm 20\text{ V}$			± 80	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60\text{ V}, V_{GS}=0\text{ V}$			80	nA
On-state Drain Current	$I_{D(on)}$	$V_{GS}=10\text{ V}, V_{DS}=7\text{ V}$	500			mA
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=500\text{mA}$		0.9	5	Ω
		$V_{GS}=5\text{ V}, I_D=50\text{mA}$		1.1	7	
Forward Trans conductance	g_{fs}	$V_{DS}=10\text{ V}, I_D=200\text{mA}$	80			ms
Drain-source on-voltage	$V_{DS(on)}$	$V_{GS}=10\text{V}, I_D=500\text{mA}$			3.75	V
		$V_{GS}=5\text{V}, I_D=50\text{mA}$			0.375	V
Diode Forward Voltage	V_{SD}	$I_S=115\text{mA}, V_{GS}=0\text{ V}$	0.55		1.2	V
Input Capacitance *	C_{iss}	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$			50	pF
Output Capacitance *	C_{oss}				25	
Reverse Transfer Capacitance*	C_{rss}				5	

SWITCHING TIME

Turn-on Time*	$t_{d(on)}$	$V_{DD}=25\text{ V}, R_L=50\Omega,$ $I_D=500\text{mA}, V_{GEN}=10\text{ V}$ $R_G=25\Omega$			20	ns
Turn-off Time*	$t_{d(off)}$				40	

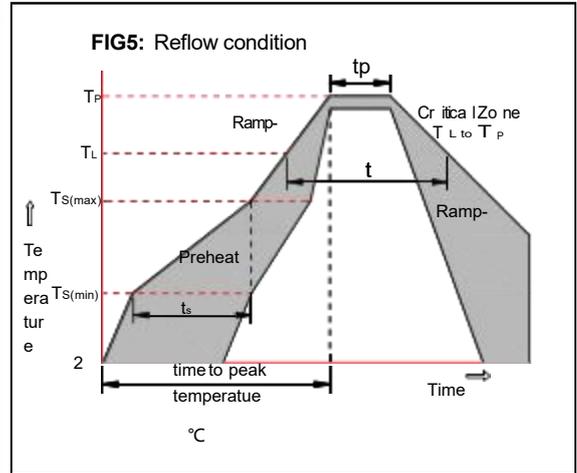
*These parameters have no way to verify.

RATING AND CHARACTERISTIC CURVES



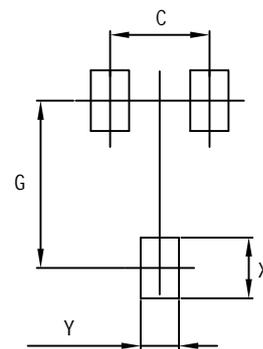
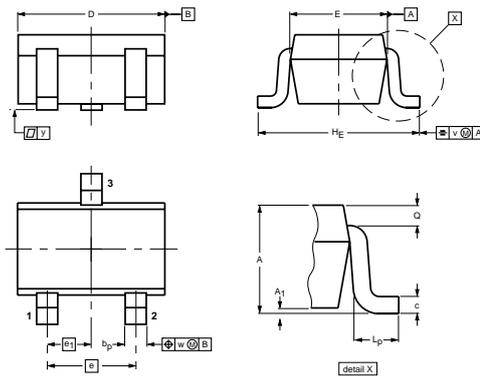
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

SOT-323

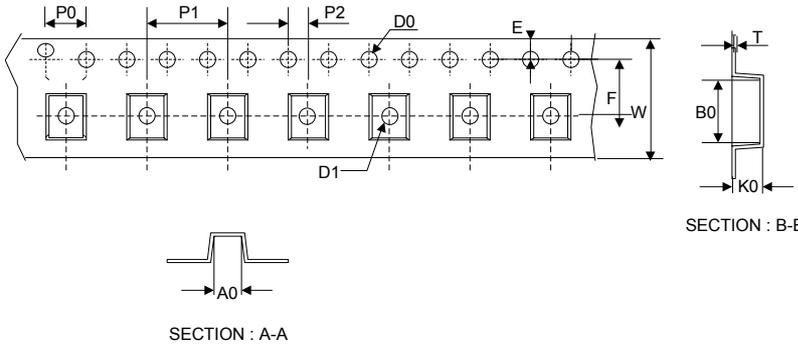
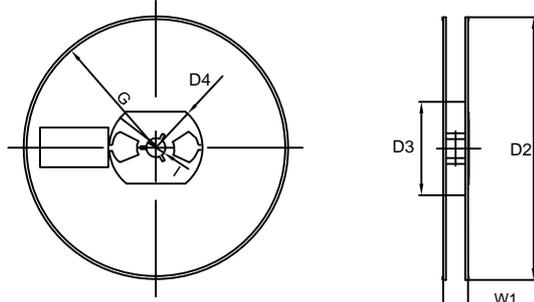


Dimensions	Value (in mm)
C	1.30
G	2.00
X	0.90
Y	0.65

DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

Tape & reel specification

Tape	Symbol	Dimension (mm)	
	P0	4.00±0.20	
	P1	4.00±0.20	
	P2	2.00±0.20	
	D0	1.55±0.20	
	D1	1.00±0.20	
	E	1.55±0.25	
	F	3.60±0.20	
	W	8.00±0.20	
	A0	2.50±0.20	
	B0	2.60±0.20	
	K0	1.40±0.20	
	T	0.20±0.20	
	7" Reel	D2	177.0±5.0
		D3	55Min.
		D4	R24.6±2.0
		G	R82.0±2.0
		I	13.0±2.0
W1		10.20±3.0	
Quantity: 3000PCS			